

# KPS HV, Large Case, SM Series, COG Dielectric, 500 – 10,000 VDC (Industrial Grade)

## Overview

KPS HV (KEMET Power Solutions, High Voltage), Large Case ( $\geq 1515$ ), SM Series capacitors in COG dielectric are designed to meet robust performance standards required in higher reliability industrial applications. Utilizing lead-frame technology, SM Series devices isolate the multilayer ceramic chip component from the printed circuit board providing advanced mechanical and thermal stress performance. Isolation of the chip component also addresses concerns for audible, microphonic noise that may occur when a bias voltage is applied. Although this technology does not eliminate the potential for mechanical damage that may propagate during extreme environmental and handling conditions, it does demonstrate superior performance over non-isolating systems. Available in both formed "L" and "J" lead configurations, SM Series devices

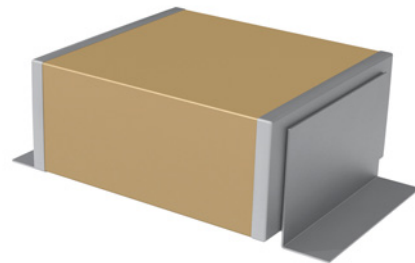
offer up to 10 mm of board flex capability and exhibit lower ESR, ESL and higher current discharge capability when compared to other dielectric solutions.

Combined with the stability of an COG dielectric, KEMET's High Voltage SM Series devices exhibit no change in capacitance with respect to time and voltage and boasts a negligible change in capacitance with reference to ambient temperature. Capacitance change is limited to  $\pm 30$  ppm/ $^{\circ}\text{C}$  from  $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ .

KEMET's Industrial Grade products offer additional screening options for higher reliability applications. Both Group A and Group B testing/inspection options per MIL-PRF-49467 are available for the SM Series.

## Benefits

- $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  operating temperature range
- Large Case Sizes ( $\geq 1515$ )
- Formed "L" or "J" leadframe configurations.
- Group A and B screening per MIL-PRF-49467 available
- Reliable and robust leadframe termination system
- DC voltage ratings of 500 V, 1 KV, 2 KV, 3 KV, 4 KV, 5 KV, 7.5 KV, and 10 KV
- Capacitance offerings ranging from 10 pF up to 0.39  $\mu\text{F}$



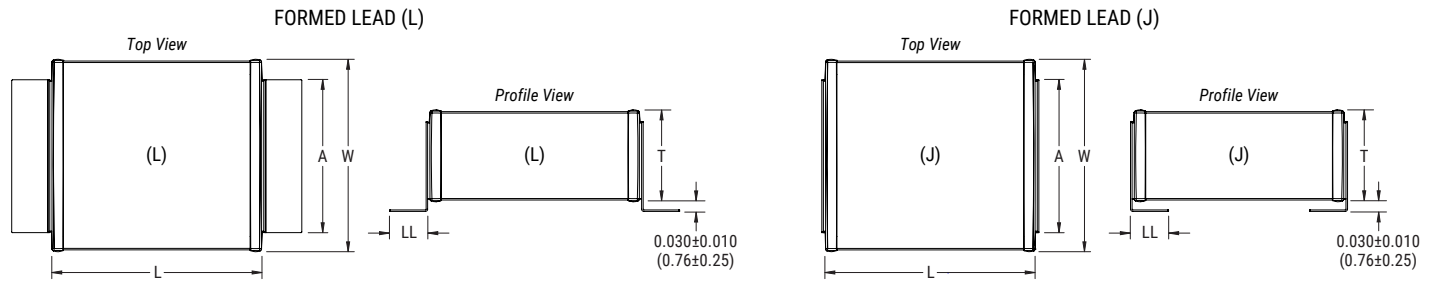
## Ordering Information

SM20		N	472	J	501	B	M
Style/Size		Dielectric	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Lead Configuration <sup>1</sup>	Testing/ Inspection Option <sup>2</sup>
SM20	SM30	N = COG	Two significant digits and number of zeros	J = $\pm 5\%$	501 = 500	A = Formed L B = Formed J	Blank = None M = Group A per MIL-PRF-49467
SM21	SM31			K = $\pm 10\%$	102 = 1,000		
SM22	SM33			M = $\pm 20\%$	202 = 2,000		
SM23	SM34			P = 0/+100%	302 = 3,000		
SM24	SM35			Z = -20%/+80%	402 = 4,000		
SM25	SM36				502 = 5,000		
SM26					752 = 7,500 103 = 10,000		

<sup>1</sup> Standard lead configuration is formed "J". If the appropriate character is excluded from the ordering code, the assumed lead configuration will be formed "J".

<sup>2</sup> Group B testing/inspection option per MIL-PRF-49467 is available upon request. Please contact KEMET for ordering details.

## Dimensions – Inches (Millimeters)



Style/ Size	L Length	W Width	T Thickness Maximum	A Lead Width Maximum	LL Lead Length (Formed "L")	LL Lead Length (Formed "J")	
SM20	0.150±0.015 (3.81±0.38)	0.150±0.015 (3.81±0.38)	0.130 (3.30)	0.100 (2.54)	0.100±0.020 (2.54±0.51)	0.040±0.010 (1.02±0.25)	
SM21	0.200±0.020 (5.08±0.51)	0.200±0.020 (5.08±0.51)	0.180 (4.57)				
SM22	0.250±0.020 (6.35±0.51)	0.200±0.020 (5.08±0.51)	0.220 (5.59)	0.200 (5.08)		0.100±0.020 (2.54±0.51)	
SM23	0.350±0.030 (8.89±0.76)	0.300±0.030 (7.62±0.76)		0.300 (7.62)			
SM24	0.450±0.030 (11.43±0.76)	0.400±0.030 (10.20±0.76)		0.400 (10.20)			
SM25	0.550±0.030 (14.00±0.76)	0.500±0.030 (12.70±0.76)	0.500 (12.70)	0.100 (2.54)			0.100±0.020 (2.54±0.51)
SM26	0.650±0.030 (16.50±0.76)	0.600±0.030 (15.20±0.76)	0.220 (5.59)				
SM30	0.300±0.030 (7.62±0.76)	0.150±0.015 (3.81±0.38)	0.140 (3.55)	0.100 (2.54)			0.100±0.020 (2.54±0.51)
SM31	0.400±0.030 (10.20±0.76)	0.200±0.020 (5.08±0.51)	0.130 (3.30)				
SM33	0.700±0.030 (17.08±0.76)	0.300±0.030 (7.62±0.76)	0.180 (4.57)	0.200 (5.08)		0.220 (5.59)	
SM34	0.900±0.030 (22.90±0.76)	0.400±0.030 (10.20±0.76)	0.220 (5.59)	0.300 (7.62)			
SM35	1.100±0.030 (27.90±0.76)	0.500±0.030 (12.70±0.76)		0.400 (10.2)			
SM36	1.350±0.030 (33.00±0.76)	0.600±0.030 (15.20±0.76)	0.220 (5.59)	0.500 (12.7)			

## Benefits cont.

- Advanced protection against thermal and mechanical stress
- Provides up to 10 mm of board flex capability
- Reduces audible, microphonic noise
- Low ESR and ESL
- Non-polar device, minimizing installation concerns
- Silver plated copper alloy leadframe termination system

## Applications

- High frequency power converters
- Wide bandgap (WBG), silicon carbide (SiC) and gallium nitride (GaN) systems
- Snubber (high dV/dT)
- Resonant circuits (LLC, Wireless Charging, etc)
- Timing
- Filtering

## Qualification/Certification

Industrial Grade products are subject to internal qualification. Details regarding test methods and conditions are referenced in Table 3, Performance & Reliability.

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## Environmental Compliance

RoHS Compliant with Exemption(s).





**Table 1C – Capacitance Range/Selection Waterfall SM33 – SM35 Style/Size**

Style/Size			SM33							SM34							SM35									
Voltage Code			501	102	202	302	402	502	752	501	102	202	302	402	502	752	501	102	202	302	402	502	752	103		
Voltage DC			500	1 K	2 K	3 K	4 K	5 K	7.5 K	500	1 K	2 K	3 K	4 K	5 K	7.5 K	500	1 K	2 K	3 K	4 K	5 K	7.5 K	10 K		
Capacitance	Capacitance Code	Capacitance Tolerance	Capacitance Code																							
27 pF	270	J K M P Z	X	X	X	X	X	X	X																	
33 pF	330	J K M P Z	X	X	X	X	X	X	X																	
39 pF	390	J K M P Z	X	X	X	X	X	X	X																	
47 pF	470	J K M P Z	X	X	X	X	X	X	X					X	X	X										
56 pF	560	J K M P Z	X	X	X	X	X	X	X					X	X	X										
68 pF	680	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X										
82 pF	820	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X										
100 pF	101	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X										
120 pF	121	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X										
150 pF	151	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X										
180 pF	181	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X										
220 pF	221	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X			
270 pF	271	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X			
330 pF	331	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X			
390 pF	391	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X			
470 pF	471	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X			
560 pF	561	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X			
680 pF	681	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X			
820 pF	821	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X			
1,000 pF	102	J K M P Z	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X		
1,200 pF	122	J K M P Z	X	X	X	X	X	X		X	X	X	X	X	X		X	X	X	X	X	X	X			
1,500 pF	152	J K M P Z	X	X	X	X	X	X		X	X	X	X	X	X		X	X	X	X	X	X	X			
1,800 pF	182	J K M P Z	X	X	X	X				X	X	X	X	X	X		X	X	X	X	X	X	X			
2,200 pF	222	J K M P Z	X	X	X	X				X	X	X	X	X	X		X	X	X	X	X	X	X			
2,700 pF	272	J K M P Z	X	X	X	X				X	X	X	X	X	X		X	X	X	X	X	X	X			
3,300 pF	332	J K M P Z	X	X	X	X				X	X	X	X				X	X	X	X	X	X	X			
3,900 pF	392	J K M P Z	X	X	X	X				X	X	X	X				X	X	X	X	X	X	X			
4,700 pF	472	J K M P Z	X	X	X	X				X	X	X	X				X	X	X	X	X	X	X			
5,600 pF	562	J K M P Z	X	X	X	X				X	X	X	X				X	X	X	X	X	X	X			
6,800 pF	682	J K M P Z	X	X	X	X				X	X	X	X				X	X	X	X	X	X	X			
7,500 pF	752	J K M P Z	X	X	X					X	X	X	X				X	X	X	X						
8,200 pF	822	J K M P Z	X	X	X					X	X	X	X				X	X	X	X						
0.01 µF	103	J K M P Z	X	X	X					X	X	X	X				X	X	X	X						
0.012 µF	123	J K M P Z	X	X	X					X	X	X	X				X	X	X	X						
0.015 µF	153	J K M P Z	X	X	X					X	X	X	X				X	X	X	X						
0.018 µF	183	J K M P Z	X	X	X					X	X	X					X	X	X	X						
0.022 µF	223	J K M P Z	X	X						X	X	X					X	X	X	X						
0.027 µF	273	J K M P Z	X	X						X	X						X	X	X							
0.033 µF	333	J K M P Z	X	X						X	X						X	X	X							
0.039 µF	393	J K M P Z	X	X						X	X						X	X	X							
0.047 µF	473	J K M P Z	X	X						X	X						X	X	X							
0.056 µF	563	J K M P Z	X							X	X						X	X								
0.068 µF	683	J K M P Z	X							X							X	X								
0.082 µF	823	J K M P Z	X							X							X	X								
0.100 µF	104	J K M P Z	X							X							X	X								
0.120 µF	124	J K M P Z								X							X	X								
0.150 µF	154	J K M P Z								X							X	X								
0.180 µF	184	J K M P Z															X									
0.220 µF	224	J K M P Z															X									
0.270 µF	274	J K M P Z															X									

**Table 1D – Capacitance Range/Selection Waterfall SM36 Style/Size**

Style/Size			SM36										
Voltage Code			501	102	202	302	402	502	752	103			
Voltage DC			500	1K	2K	3K	4K	5K	7.5K	10K			
Capacitance	Capacitance Code	Capacitance Tolerance			Capacitance Code								
270 pF	271	J	K	M	P	Z	X	X	X	X	X	X	
330 pF	331	J	K	M	P	Z	X	X	X	X	X	X	
390 pF	391	J	K	M	P	Z	X	X	X	X	X	X	
470 pF	471	J	K	M	P	Z	X	X	X	X	X	X	
560 pF	561	J	K	M	P	Z	X	X	X	X	X	X	
680 pF	681	J	K	M	P	Z	X	X	X	X	X	X	
820 pF	821	J	K	M	P	Z	X	X	X	X	X	X	
1,000 pF	102	J	K	M	P	Z	X	X	X	X	X	X	
1,200 pF	122	J	K	M	P	Z	X	X	X	X	X	X	
1,500 pF	152	J	K	M	P	Z	X	X	X	X	X	X	X
1,800 pF	182	J	K	M	P	Z	X	X	X	X	X	X	
2,200 pF	222	J	K	M	P	Z	X	X	X	X	X	X	
2,700 pF	272	J	K	M	P	Z	X	X	X	X	X	X	
3,300 pF	332	J	K	M	P	Z	X	X	X	X	X	X	
3,900 pF	392	J	K	M	P	Z	X	X	X	X	X	X	
4,700 pF	472	J	K	M	P	Z	X	X	X	X	X	X	
5,600 pF	562	J	K	M	P	Z	X	X	X	X	X	X	
6,800 pF	682	J	K	M	P	Z	X	X	X	X	X	X	
7,500 pF	752	J	K	M	P	Z	X	X	X	X	X	X	
8,200 pF	822	J	K	M	P	Z	X	X	X	X	X	X	
0.01 µF	103	J	K	M	P	Z	X	X	X	X	X	X	
0.012 µF	123	J	K	M	P	Z	X	X	X	X	X	X	
0.015 µF	153	J	K	M	P	Z	X	X	X	X	X	X	
0.018 µF	183	J	K	M	P	Z	X	X	X	X	X	X	
0.022 µF	223	J	K	M	P	Z	X	X	X	X	X	X	
0.027 µF	273	J	K	M	P	Z	X	X	X	X	X	X	
0.033 µF	333	J	K	M	P	Z	X	X	X	X	X	X	
0.039 µF	393	J	K	M	P	Z	X	X	X	X	X	X	
0.047 µF	473	J	K	M	P	Z	X	X	X	X	X	X	
0.056 µF	563	J	K	M	P	Z	X	X	X	X	X	X	
0.068 µF	683	J	K	M	P	Z	X	X	X	X	X	X	
0.082 µF	823	J	K	M	P	Z	X	X	X	X	X	X	
0.1 µF	104	J	K	M	P	Z	X	X	X	X	X	X	
0.12 µF	124	J	K	M	P	Z	X	X	X	X	X	X	
0.15 µF	154	J	K	M	P	Z	X	X	X	X	X	X	
0.18 µF	184	J	K	M	P	Z	X	X	X	X	X	X	
0.22 µF	224	J	K	M	P	Z	X	X	X	X	X	X	
0.27 µF	274	J	K	M	P	Z	X	X	X	X	X	X	
0.33 µF	334	J	K	M	P	Z	X	X	X	X	X	X	
0.39 µF	394	J	K	M	P	Z	X	X	X	X	X	X	

**Table 2 – Chip Thickness/Packaging Quantities**

Series	Style/Size	Tray Quantity Minimum <sup>1</sup>	Tray Quantity Maximum <sup>1</sup>
SM	SM20	1	50
	SM21		
	SM22		
	SM23		
	SM24		
	SM25		
	SM26		
	SM30		
	SM31		
	SM33		
	SM34		10
	SM35		
	SM36		

<sup>1</sup> Minimum order value applies. Contact KEMET for details.

## Soldering Process

The capacitors and assemblies outlined in this specification sheet are susceptible to thermal shock damage due to their large ceramic mass. Temperature profiles used should provide adequate temperature rise and cool-down time to prevent damage from thermal shock. In general, KEMET recommends against hand soldering for these types of large ceramic devices.

### Recommended Soldering Technique:

- Solder reflow only

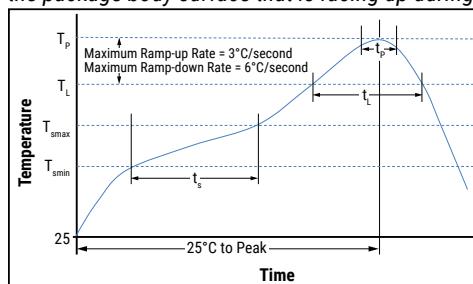
### Preheating and Reflow Profile Notes:

Due to differences in the coefficient of thermal expansion for the different materials of construction, it is critical to monitor and control the heating and cooling rates during the soldering process. During the reflow soldering process, the maximum recommended heating and cooling rate ( $dT/dt$ ) is 4°C/second. To ensure optimal component reliability, KEMET's recommended heating and cooling rate is 2°C/second. After soldering, the capacitors should be air cooled to room temperature before further processing. Forced air cooling is not recommended.

### Recommended Reflow Soldering Profile:

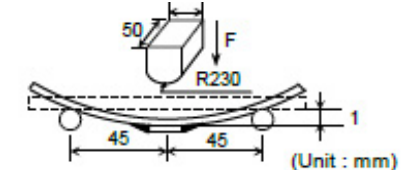
Profile Feature	SnPb Assembly
<b>Preheat/Soak</b>	
Temperature Minimum ( $T_{smin}$ )	100°C
Temperature Maximum ( $T_{smax}$ )	150°C
Time ( $t_s$ ) from $T_{smin}$ to $T_{smax}$	60 – 90 seconds
Ramp-up Rate ( $T_L$ to $T_p$ )	2°C/seconds
Liquidous Temperature ( $T_L$ )	183°C
Time Above Liquidous ( $t_L$ )	95 seconds
Peak Temperature ( $T_p$ )	240°C
Time within 5°C of Maximum Peak Temperature ( $t_p$ )	5 seconds
Ramp-down Rate ( $T_p$ to $T_L$ )	2°C/seconds
Time 25°C to Peak Temperature	3.5 minutes

Note 1: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow.





**Table 3 – Performance & Reliability: Test Methods and Conditions**

TEST	REFERENCE	Test Condition	LIMITS										
Visual & Mechanical	KEMET Internal	No defects that may affect performance (10X)	Dimensions according KEMET Spec Sheet										
Capacitance (Cap)	KEMET Internal	$C \leq 1000 \text{ pF}$ Frequency: 1 MHz $\pm 100 \text{ kHz}$ Voltage*: 1.0 Vrms $\pm 0.2 \text{ V}$ $C > 1,000 \text{ pF}$ Frequency: 1 kHz $\pm 50 \text{ Hz}$ Voltage: 1.0 Vrms $\pm 0.2 \text{ V}$ * See part number specification sheet for voltage	Within Tolerance										
Dissipation Factor (DF)	KEMET Internal	$C \leq 1000 \text{ pF}$ Frequency: 1 MHz $\pm 100 \text{ kHz}$ Voltage*: 1.0 Vrms $\pm 0.2 \text{ V}$ $C > 1,000 \text{ pF}$ Frequency: 1 kHz $\pm 50 \text{ Hz}$ Voltage: 1.0 Vrms $\pm 0.2 \text{ V}$ * See part number specification sheet for voltage	Within Specification Dissipation factor (DF) maximum limit at 25°C = 0.15%										
Insulation Resistance (IR)	KEMET Internal	500VDC applied for 120 $\pm$ 5 seconds at 25°C	Within Specification To obtain IR limit, divide M $\Omega$ - $\mu\text{F}$ value by the capacitance and compare to G $\Omega$ limit. Select the lower of the two limits: 1,000 megohm microfarads or 100 G $\Omega$ .										
Temperature Coefficient of Capacitance (TCC)	KEMET Internal	Capacitance change with reference to +25°C and 0 VDC applied. * See part number specification sheet for voltage <table border="1" style="margin: 10px auto;"> <thead> <tr> <th>Step</th> <th>Temperature (°C)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>+25°C</td> </tr> <tr> <td>2</td> <td>-55°C</td> </tr> <tr> <td>3</td> <td>+25°C (Reference Temperature)</td> </tr> <tr> <td>4</td> <td>+125°C</td> </tr> </tbody> </table>	Step	Temperature (°C)	1	+25°C	2	-55°C	3	+25°C (Reference Temperature)	4	+125°C	Within Specification: $\pm 30 \text{ ppm} / ^\circ\text{C}$
Step	Temperature (°C)												
1	+25°C												
2	-55°C												
3	+25°C (Reference Temperature)												
4	+125°C												
Dielectric Withstanding Voltage (DWV)	KEMET Internal	150% of rated voltage for voltage rating of $\leq 1,250 \text{ VDC}$ 120% of rated voltage for voltage rating of $> 1,250 \text{ VDC}$ (5 $\pm$ 1 seconds and charge/discharge not exceeding 50 mA)	Withstand test voltage without insulation breakdown or damage.										
Aging Rate (Maximum % Capacitance Loss/Decade Hour)	KEMET Internal	Maximum % capacitance loss/decade hour	0% Loss/Decade Hour										
Terminal Strength	MIL-STD-202 Method 211	Conditions A (2.3 kg or 5 lbs).	No evidence of mechanical damage										
Board Flex	AEC-Q200-005	Standard Termination system 2.0 mm Flexible Termination System 3.0 mm Test time: 60 $\pm$ 5sec Ramp time: 1 mm / sec 	No evidence of mechanical damage										

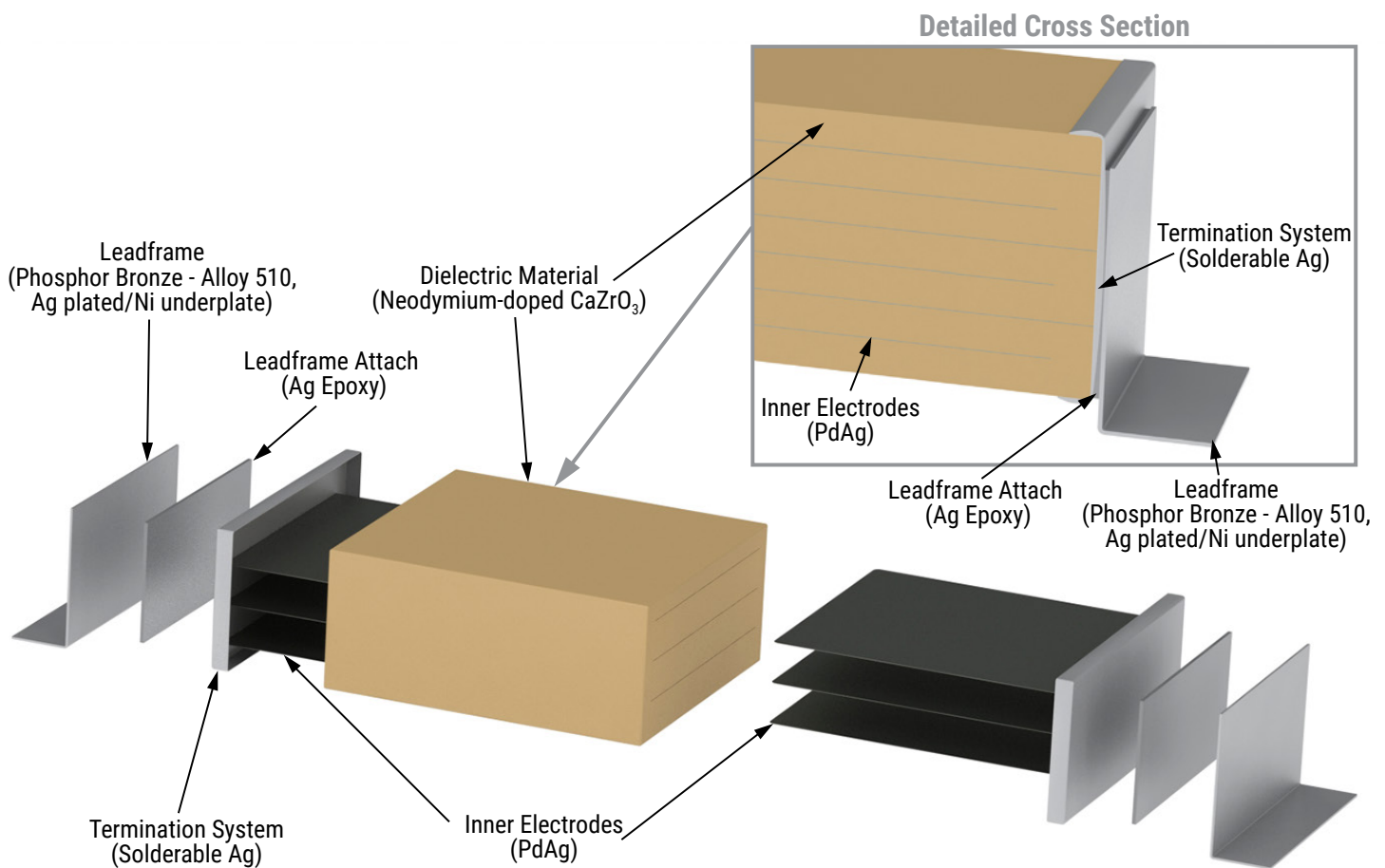
**Table 3 – Performance & Reliability: Test Methods and Conditions cont.**

Solderability	J-STD-002	Condition: 4 hours ± 15 minutes at 155°C dry bake apply all methods Test 245 ±5°C (SnPb & Pb-Free)	Visual Inspection. 95% coverage on termination. No leaching
Temperature Cycling	JESD22 Method JA-104	1,000 cycles (-55°C to +125°C) 2-3 cycles per hour Soak Time 1 or 5 min	Measurement at 24 hours ±4 hours after test conclusion. Cap: ±0.3% or ±0.25 pF shift DF: Initial Limit IR: Initial Limit
Biased Humidity	MIL-STD-202 Method 103	Load Humidity: 1,000 hours 85°C / 85% RH and 200 VDC maximum	Measurement at 24 hours ±4 hours after test conclusion. Within Post Environmental Limits Cap: ±0.3% or ±0.25 pF shift IR: 10% of Initial Limit DF Limits Maximum: 0.5%
		Low Volt Humidity: 1,000 hours 85°C / 85% RH and 1.5 V.	
Moisture Resistance	MIL-STD-202 Method 106	Number of cycles required 10, 24 hours per cycle. Steps 7a and 7b not required	Cap: ±0.3% or ±0.25 pF shift IR: 10% of Initial Limit DF Limits Maximum: 0.5%
Thermal Shock	MIL-STD-202 Method 107	Number of cycles required 5, (-55°C to 125°C) Dwell time 15 minutes.	Cap: ±0.3% or ±0.25 pF shift DF: Initial Limit IR: Initial Limit
High Temperature Life	MIL-STD-202 Method 108	1,000 hours at 125°C with rated voltage applied.	Within Post Environmental Limits Cap: ±0.3% or ±0.25 pF shift IR: 10% of Initial Limit DF Limits Maximum: 0.5%
Vibration	MIL-STD-202 Method 204	5 g's for 20 minutes, 12 cycles each of 3 orientations. Test from 10 – 2,000 Hz	Cap: ±0.3% or ±0.25 pF shift DF: Initial Limit IR: Initial Limit
Mechanical Shock	MIL-STD-202 Method 213	1500g's 0.5ms Half-sine, Velocity Change 15.4 ft/sec (Condition F)	Cap: ±0.3% or ±0.25 pF shift DF: Initial Limit IR: Initial Limit
Resistance to Soldering Heat	MIL-STD-202 Method 210	Condition K, time above 217°C, 60s – 150s	Cap: ±0.3% or ±0.25 pF shift DF: Initial Limit IR: Initial Limit

## Storage and Handling

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature—reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years of receipt.

## Construction



## Product Marking

Product marking is an extra-cost option. These devices will be supplied unmarked unless otherwise specified and/or requested. For more detailed information regarding marked product and how to request this option, please contact KEMET.

## KEMET Electronics Corporation Sales Offices

For a complete list of our global sales offices, please visit [www.kemet.com/sales](http://www.kemet.com/sales).

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